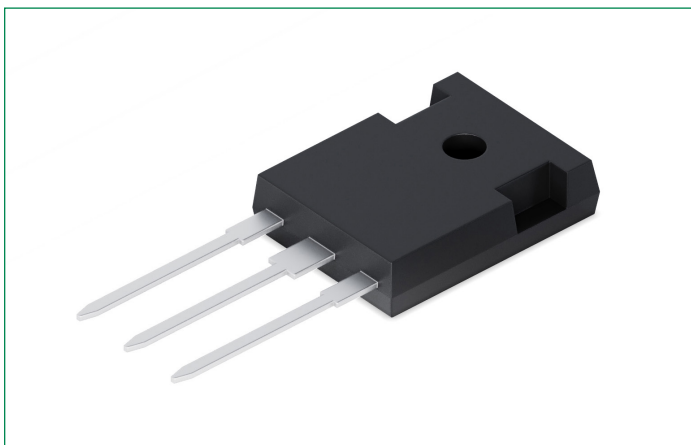


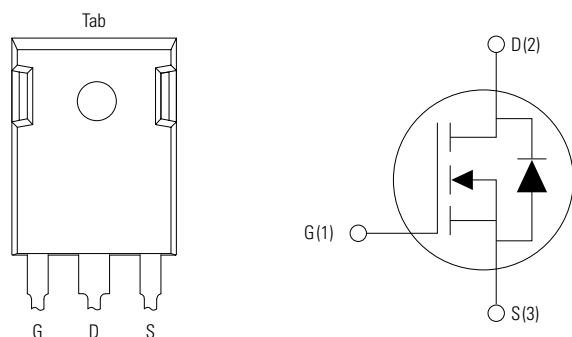
IXFH46N65X2W

650 V, 46 A, 69 mΩ, X2 Class HiPerFET™ Power MOSFET

N-Channel Enhancement Mode, Avalanche Rated



Pinout Diagram TO-247 (IXFH)



G: Gate; **D:** Drain; **S:** Source; **Tab:** Drain

Features

- International standard package
- High power density
- Low $R_{DS(on)}$ and Q_g
- Avalanche rated

Benefits

- Reduced conduction losses
- Reduced driver power requirements
- Easy to mount
- Space savings

Applications

- Switch-mode and resonant-mode power supplies
- DC-DC converters
- PFC circuits
- AC and DC motor drives
- Robotics and servo controls

Product Summary

Characteristic	Value	Unit
V_{DSS}	650	V
I_{D25}	46	A
$R_{DS(on)}$	≤ 69	mΩ

Maximum Ratings

Symbol	Characteristic	Conditions	Value	Unit
V_{DSS}	Drain-Source Voltage	$T_{vj} = 25\text{ }^{\circ}\text{C}$ to $150\text{ }^{\circ}\text{C}$	650	V
V_{GSS}	Gate-Source Voltage	–	± 30	V
V_{GSM}	Transient Gate-Source Voltage	–	± 40	
I_D	Drain Current	$T_c = 25\text{ }^{\circ}\text{C}$	46	A
I_{DM}	Peak Drain Current	$T_c = 25\text{ }^{\circ}\text{C}$, pulse width limited by $T_{vj(max)}$	92	
I_{AS}	Non-Repetitive Single Pulse Avalanche Current	$T_c = 25\text{ }^{\circ}\text{C}$	10	A
E_{AS}	Non-Repetitive Single Pulse Avalanche Energy	$T_c = 25\text{ }^{\circ}\text{C}$	1.3	J
I_S	Diode Forward Current	$V_{GS} = 0\text{ V}$	46	A
I_{SM}	Diode Peak Forward Current	Repetitive, pulse width limited by $T_{vj(max)}$	184	A
dv/dt	Diode Dv/Dt Capability	$I_S \leq I_{DM}$, $V_{DD} \leq V_{DSS}$, $T_{vj} \leq 150\text{ }^{\circ}\text{C}$	50	V/ns
P_{tot}	Total Power Dissipation	$T_c = 25\text{ }^{\circ}\text{C}$	660	W
T_{vj}	Virtual Junction Temperature Range	–	–55 to +150	$^{\circ}\text{C}$
T_{stg}	Storage Temperature Range	–	–55 to +150	
T_{sold}	Soldering Temperature	–	300	$^{\circ}\text{C}$
M_t	Mounting Torque For Terminal Screws	–	1.13 / 10	Nm/lb.in

Electrical Characteristics – Static ($T_{vj} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Symbol	Characteristic	Conditions	Value			Unit
			Min.	Typ.	Max.	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$	650	–	–	V
$V_{GS(th)}$	Gate-Source Threshold Voltage	$I_D = 4\text{ mA}$, $V_{GS} = V_{DS}$	3.5	–	5.5	V
I_{GSS}	Gate Leakage Current	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 30\text{ V}$	–	–	± 100	nA
I_{DSS}	Drain-Source Leakage Current	$V_{DS} = V_{DSS}$, $V_{GS} = 0\text{ V}$	–	–	25	μA
		$V_{DS} = V_{DSS}$, $V_{GS} = 0\text{ V}$, $T_{vj} = 125\text{ }^{\circ}\text{C}$	–	–	2	mA
$R_{DS(on)}$	Drain-Source On-Resistance ¹	$V_{GS} = 10\text{ V}$, $I_D = 0.5 \times I_{D25}$	–	–	69	m Ω

Note 1: Pulse test, $t \leq 300\text{ }\mu\text{s}$, duty cycle, $d \leq 2\%$

Electrical Characteristics – Dynamic ($T_{vj} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)

Symbol	Characteristic	Conditions	Value			Unit
			Min.	Typ.	Max.	
g_{fs}	Transconductance ¹	$V_{DS} = 10\text{ V}$, $I_D = 0.5 \times I_{D25}$	24	38	–	S
$R_{g(int)}$	Internal Gate Resistance	–	–	0.9	–	Ω
C_{iss}	Input Capacitance	$V_{GS} = 0\text{ V}$, $V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$	–	4640	–	pF
C_{oss}	Output Capacitance		–	2070	–	
C_{rss}	Reverse Transfer Capacitance		–	1.6	–	
$C_{o(er)}$	Effective Output Capacitance – Energy Related	$V_{GS} = 0\text{ V}$, $V_{DS} = 0.8 \times V_{DSS}$	–	173	–	pF
$C_{o(tr)}$	Effective Output Capacitance – Time Related		–	634	–	
Q_G	Total Gate Charge	$V_{GS} = 10\text{ V}$, $V_{DS} = 0.5 \times V_{DSS}$, $I_D = 0.5 \times I_{D25}$	–	90	–	nC
Q_{GS}	Gate-Source Charge		–	29	–	
Q_{GD}	Gate-Drain Charge		–	32	–	
$t_{d(on)}$	Turn-On Delay Time	Resistive Switching, $V_{GS} = 10\text{ V}$, $V_{DS} = 0.5 \times V_{DSS}$, $I_D = 0.5 \times I_{D25}$, $R_{G(ext)} = 3\text{ }\Omega$	–	28	–	ns
t_r	Rise Time		–	21	–	
$t_{d(off)}$	Turn-Off Delay Time		–	53	–	
t_f	Fall Time		–	12	–	

Note 1: Pulse test, $t \leq 300\text{ }\mu\text{s}$, duty cycle, $d \leq 2\%$

Electrical Characteristics - Body diode ($T_{vj} = 25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Characteristic	Conditions	Value			Unit
			Min.	Typ.	Max.	
V_{SD}	Diode Forward Voltage ¹	$I_F = I_S, V_{GS} = 0\text{ V}$	–	–	1.4	V
t_{rr}	Reverse Recovery Time	$I_F = 23\text{ A}, -di_S/dt = 100\text{ A}/\mu\text{s},$ $V_R = 100\text{ V}, V_{GS} = 0\text{ V}$	–	206	–	ns
Q_{rr}	Reverse Recovery Charge		–	1.90	–	μC
I_{rrm}	Peak Reverse Recovery Current		–	18.6	–	A

Note 1: Pulse test, $t \leq 300\text{ }\mu\text{s}$, duty cycle, $d \leq 2\%$

Thermal Characteristics

Symbol	Characteristic	Value			Unit
		Min.	Typ.	Max.	
$R_{th(j-c)}$	Thermal Resistance Junction To Case - MOSFET	–	–	0.19	K/W
$R_{th(c-h)}$	Thermal Resistance Case To Heat Sink - MOSFET	–	0.21	–	K/W

Package

Symbol	Characteristic	Conditions	Value			Unit
			Min.	Typ.	Max.	
G	Weight	–	–	–	6	g

Characteristic Curves

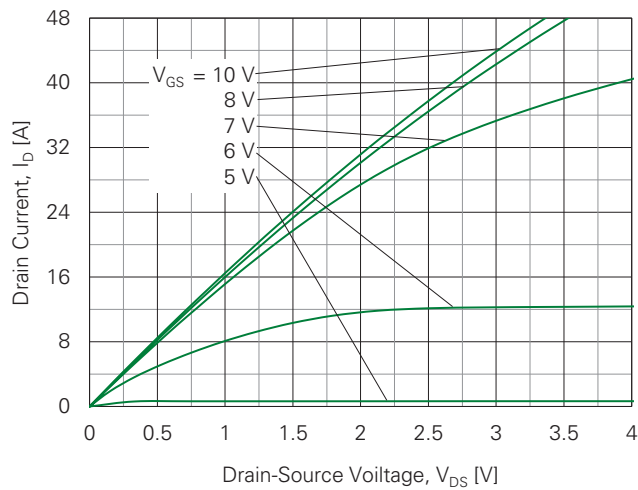
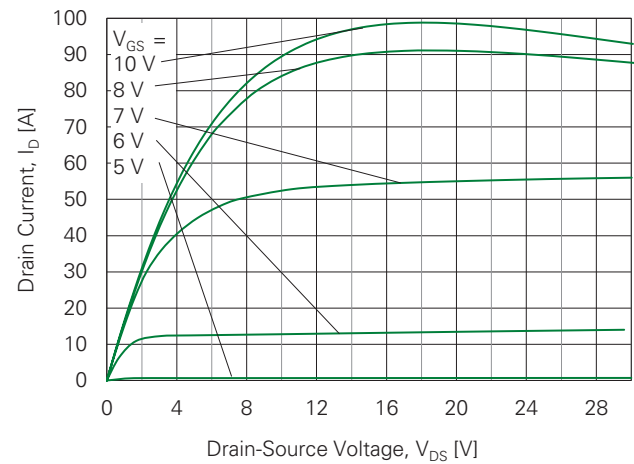
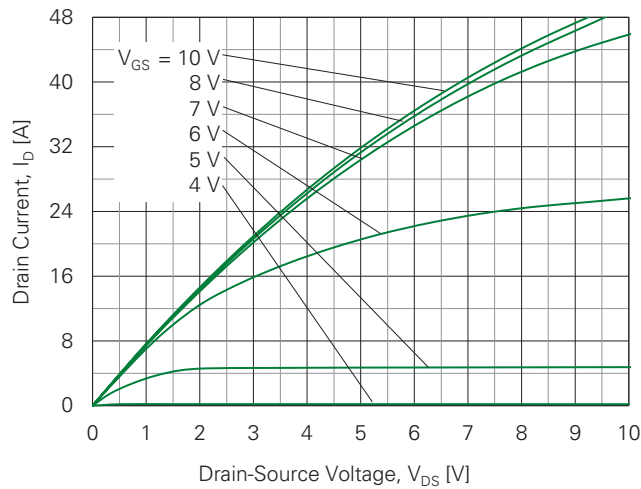
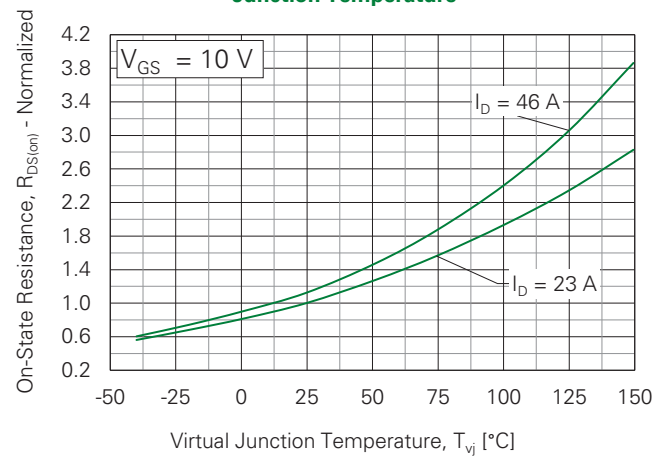
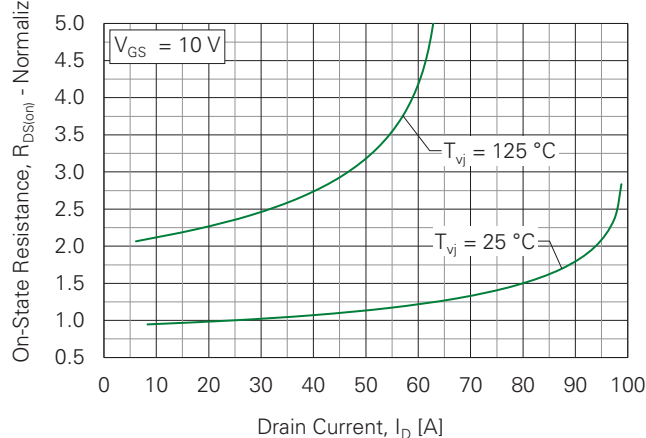
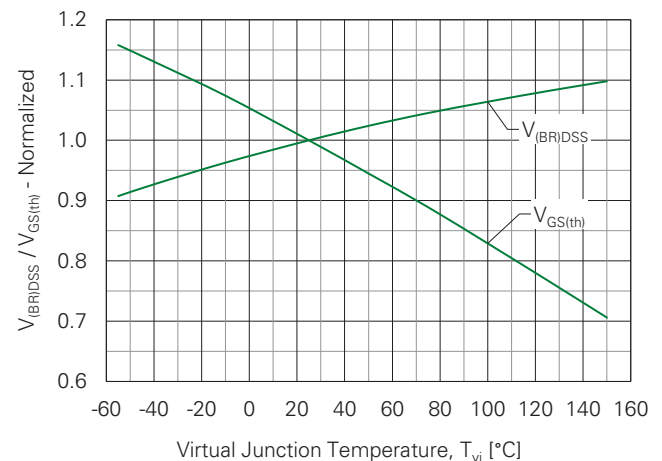
Fig. 1. Typical Output Characteristics @ $T_{vj} = 25^\circ\text{C}$ Fig. 2. Typical Extended Output Characteristics @ $T_{vj} = 25^\circ\text{C}$ Fig. 3. Typical Output Characteristics @ $T_{vj} = 125^\circ\text{C}$ Fig. 4. Typical Drain-Source On-State Resistance (Normalized to $I_D = 23\text{ A}$) vs. Virtual Junction TemperatureFig. 5. Typical Drain-Source On-State Resistance (Normalized to $I_D = 23\text{ A}$) vs. Drain CurrentFig. 6. Typical $V_{(BR)DSS}/V_{GS(th)}$ (Normalized) vs. Virtual Junction Temperature

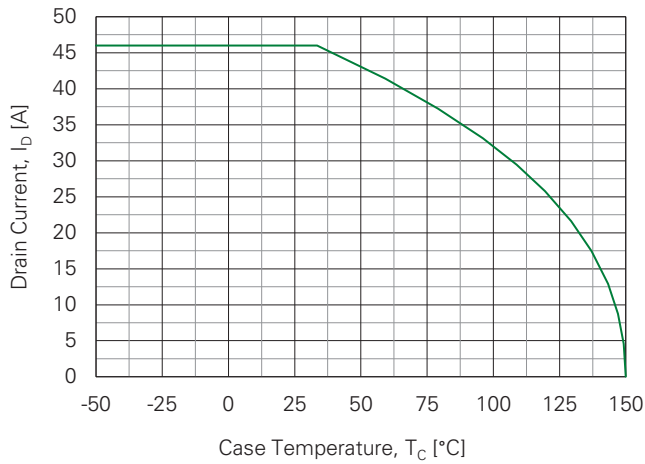
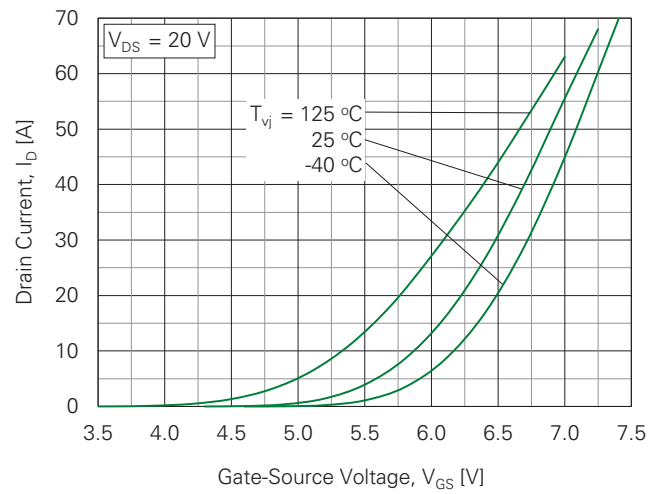
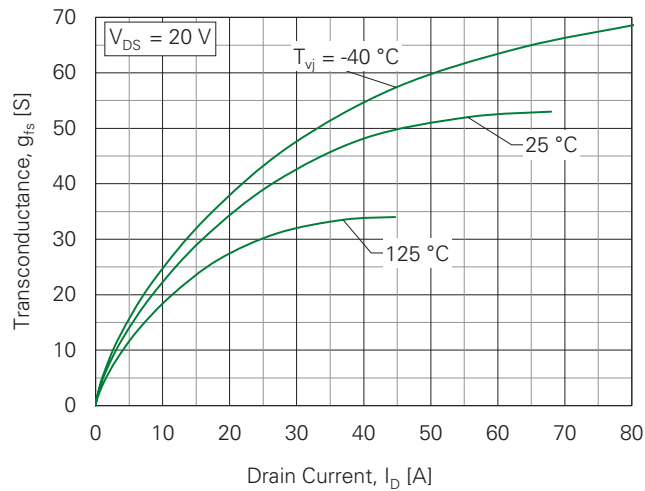
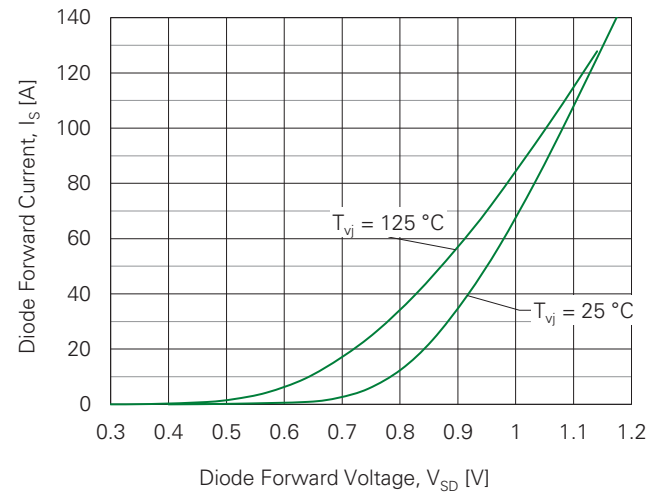
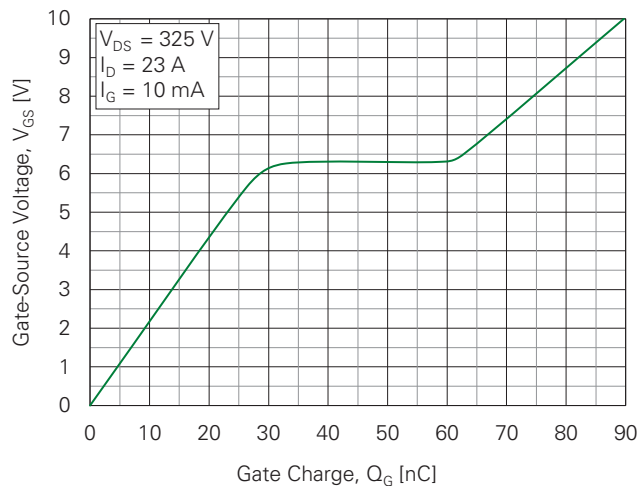
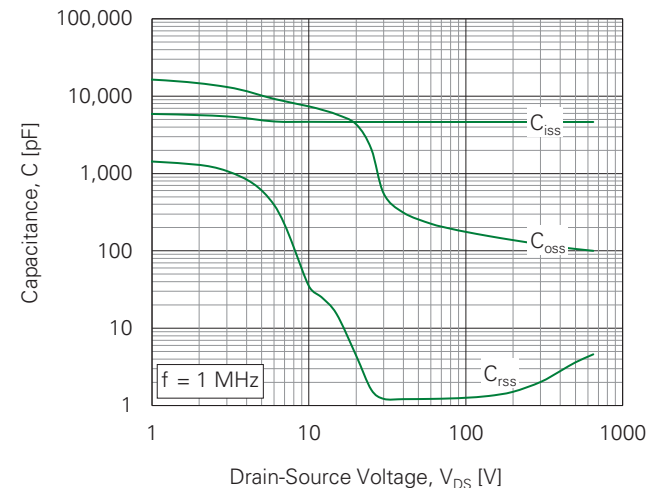
Fig. 7. Maximum Drain Current vs. Case Temperature**Fig. 8. Typical Transfer Characteristics****Fig. 9. Typical Transconductance****Fig. 10. Forward Voltage Drop of Intrinsic Diode****Fig. 11. Typical Gate Charge Characteristics****Fig. 12. Typical Junction Capacitance Characteristics**

Fig. 13. Typical Output Charge Capacitance Energy vs. Drain-Source Voltage

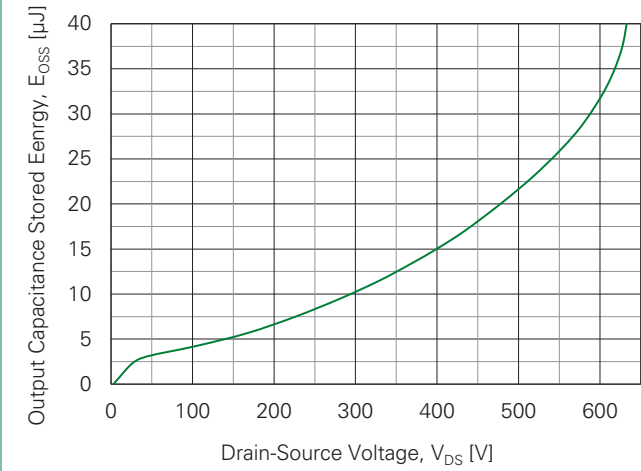


Fig. 14. Forward-Bias Safe Operating Area (FBSOA)

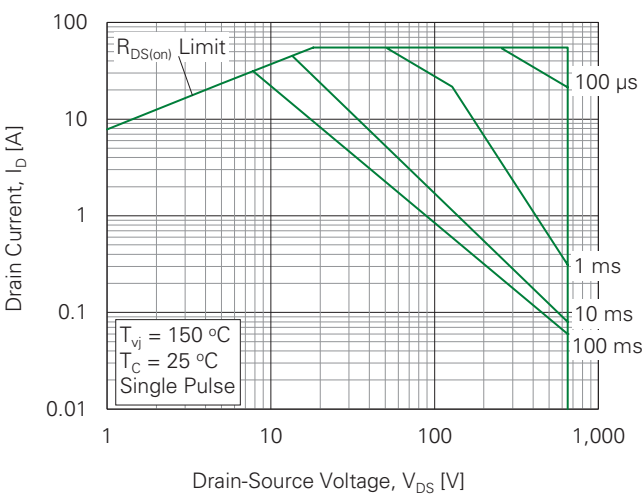
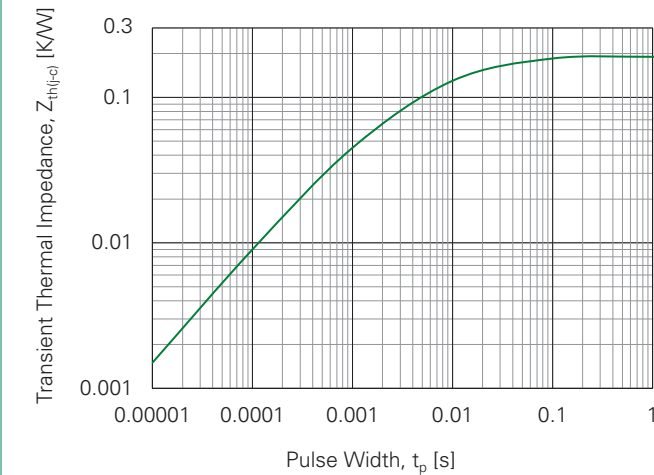
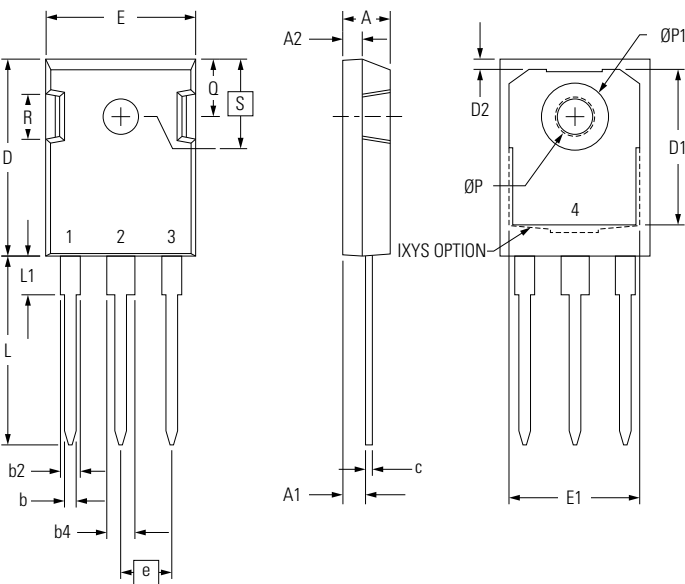


Fig. 15. Typical Transient Thermal Impedance - MOSFET



Part Outline Drawing TO-247 (IXFH)



Symbol	Inches			Millimeters		
	Min.	Typical	Max.	Min.	Typical	Max
A	0.190	–	0.205	4.83	–	5.21
A1	0.090	–	0.100	2.29	–	2.54
A2	0.075	–	0.085	1.91	–	2.16
b	0.045	–	0.055	1.14	–	1.40
b2	0.075	–	0.087	1.91	–	2.20
b4	0.115	–	0.126	2.92	–	3.20
c	0.024	–	0.031	0.61	–	0.80
D	0.819	–	0.840	20.80	–	21.34
D1	0.650	–	0.690	16.51	–	17.53
D2	0.035	–	0.050	0.89	–	1.27
E	0.620	–	0.635	15.57	–	16.13
E1	0.545	–	0.565	13.84	–	14.35
e	0.215 BSC			5.45 BSC		
L	0.780	–	0.810	19.81	–	20.57
L1	0.150	–	0.170	3.81	–	4.32
ØP	0.140	–	0.144	3.55	–	3.65
ØP1	0.275	–	0.290	6.99	–	7.37
Q	0.220	–	0.244	5.59	–	6.20
R	0.170	–	0.190	4.62	–	4.83
S	0.242 BSC			6.15 BSC		

Ordering Information

Orderable Part Number	Package Type	Shipping Form	Shipping Quantity
IXFH46N65X2	TO-247 AD	Tube	30

Disclaimer Notice

Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications.
Read complete Disclaimer Notice at <http://www.littelfuse.com/disclaimer-electronics>.



Part of:

